#### **FEATURES**

- DOUBLE LAYER CONSTRUCTION
- HIGH TEMPERATURE REFLOW (+260°C)
- SURFACE MOUNTABLE V-CHIP STYLE
- EXTENDED TEMPERATURE RANGE (UP TO +85°C FOR NEZVL)

# **RoHS** Compliant



#### **CHARACTERISTICS**

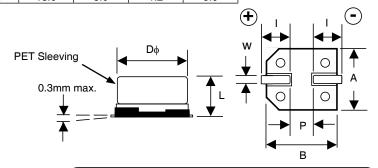
	Series			NEZVN	NEZVL	
	Operating Temperature	Range	-25°C ~ +70°C	-40°C ~ +85°C		
	Rated Capacitance R		0.047F (47,000μF), 0.1F (100,000μF) and 0.22F (220,000μF)			
	Capacitance Tolera	nce	+80%/-20% (Z)			
	Rated Voltage Ran	ige		5.5VDC		
		∆ Capacitance Change		Less than ±30% of initial measured value		
Load Life Test 1,000 hours	NEZVN @ +70°C NEZVL @ +85°C	Maximu	um ESR	Less than 400% of the sp	ecified maximum value	
1,000 110010	142242 @ 100 0	Maximum Lea	akage Current	Less than 200% of the sp	ecified maximum value	
		Δ Capacitance Change		Less than ±30% of 20°C value		
	NEZVN @ -25°C ~ +70°C	Maximum ESR		Less than 500% of 20°C value		
Characteristics		Maximum Leakage Current		Less than 400% of 20°C value		
at High & Low		Δ Capacitance Change		Less than ±30% of 20°C value		
Temperature		Maximum	-40°C	Less than 700% of 20°C value		
	NEZVL @ -40°C ~ +85°C	ESR	0.047F (47,000µF), 0.1F (100,000µF)  +80%/-20% ( 5.5VDC  Capacitance Change  Less than ±30% of initial r  Maximum ESR  Less than 200% of the specification o	of 20°C value		
		Maximum Lea	akage Current	Less than 400% of the sp	ecified maximum value	
	Vibration	Δ Capacitance Change		Less than ±10% of initial measured value		
10 ~ 5	55Hz (1 min./sweep)	Maximum ESR		Less than initial specified maximum value		
Total Amplitude	e 1.5mm, 2Hr in XYZ Directon	Maximum Leakage Current		Less than initial specified maximum value		
Resista	ince to Soldering Heat	∆ Capacita	nce Change	Less than ±10% of initial measured value		
Pe	ak Temp. +260°C	Maximum ESR		Less than initial specified maximum value		
(Time ove	er +230°C <30 seconds)	Maximum Leakage Curre		Less than initial specified maximum value		

#### STANDARD VALUES AND SPECIFICATIONS

NIC P/N	Capacitance Value (F)	Working Voltage (VDC)	Holding Voltage (VDC min.)	Max. Leakage Current after 30 minutes (μA)	Max. ESR @ 1KHz (Ω)
NEZVN473Z5.5V12.5X8.5TRF	0.047	5.5	4.0	69	30
NEZVN104Z5.5V12.5X8.5TRF	0.1	5.5	4.0	100	30
NEZVN224Z5.5V12.5X8.5TRF	0.22	5.5	4.0	135	30
NEZVL473Z5.5V12.5X10.5TRF	0.047	5.5	4.0	69	45
NEZVL104Z5.5V12.5X10.5TRF	0.1	5.5	4.0	100	45
NEZVL224Z5.5V12.5X10.5TRF	0.22	5.5	4.0	135	45

### **CASE DIMENSIONS (mm)**

		- ( ,				
Case Size	$D\phi \pm 0.5$	L max.	A/B ±0.2		W	Р
12.5X8.5	12.5	8.5	13.0	5.0	1.2	5.0
12 5X10 5	12.5	10.5	13.0	5.0	12	5.0



WASHING is NOT RECOMMENDED. Additional precautions can be found at www.niccomp.com/precautions

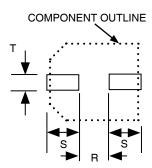
If in doubt or uncertainty, please review your specific application - process details with NIC's technical support personnel: tpmg@niccomp.com



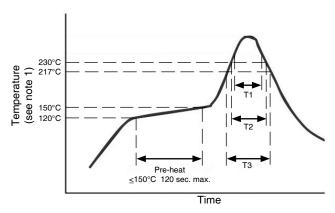
NIC COMPONENTS CORP. www.niccomp.com | www.lowESR.com | www.RFpassives.com | www.SMTmagnetics.com SPECIFICATIONS ARE SUBJECT TO CHANGE

#### LAND PATTERN DIMENSIONS (mm)

Case Diameter	R	S	Т
12.5	4.0	6.0	3.2



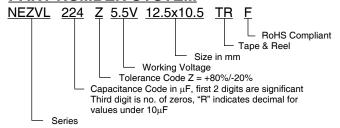
### **RECOMMENDED REFLOW PROFILE**



- 1. The temperatures shown are the surface temperature values on the top of the can and on the capacitor terminals.
- 2. 2x reflow process maximum. Capacitor should be allowed to return to room temperature before second reflow process.

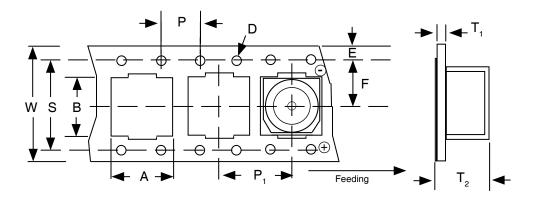
Peak Temperature	T1 Time above +230°C	T2 Time above +217°C	T3 Time above +200°C	# of times reflow
≤+260°C	≤20 seconds	≤30 seconds	≤50 seconds	2 times
≤+250°C	≤30 seconds	≤40 seconds	≤60 seconds	2 times

### **PART NUMBER SYSTEM**



## **CARRIER TAPE DIMENSIONS (mm)**

Case Size	A ± 0.2	B ± 0.2	D +1/-0	E ± 0.1	F ± 0.1	P ± 0.1	P <sub>1</sub> ± 0.1	T <sub>1</sub> ± 0.1	T <sub>2</sub> ± 0.2	W ± 0.3	Quantity/Reel
12.5 x 8.5	13.4	13.4	1.50	1.75	11.5	4.0	24.0	0.5	9.5	32.0	300
12.5 x 10.5	11.4	13.0	1.50	1.75	11.5	4.0	24.0	0.5	11.0	32.0	250



## **REEL DIMENSIONS (mm)**

Case Diameter	A max.	B min.	C ± 0.5	W	t
12.5	φ322	φ80	13.0	32.0	3.0

